

# SLOVENSKI STANDARD SIST EN IEC 62769-103-1:2020

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SIST EN 62769-103-1:2015

Vključitev procesne naprave (FDI) - 103-1. del: Profili - PROFIBUS (IEC 62769-103-1:2020)

Field Device Integration (FDI) - Part 103-1: Profiles - PROFIBUS (IEC 62769-103-1:2020)

Feldgeräteintegration (FDI) Teil 103-1: Profile - PROFIBUS (IEC 62769-103-1:2020)

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Intégration des appareils de terrain (FDI) - Partie 103-1: Profils - PROFIBUS (IEC 62769-103-1:2020)

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25.040.40 Merjenje in krmiljenje Industrial process

industrijskih postopkov measurement and control

35.240.50 Uporabniške rešitve IT v IT applications in industry

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# EUROPEAN STANDARD NORME EUROPÉENNE EUROPÄISCHE NORM

EN IEC 62769-103-1

June 2020

ICS 25.040.40; 35.100.05

Supersedes EN 62769-103-1:2015 and all of its amendments and corrigenda (if any)

#### **English Version**

# Field device integration (FDI) - Part 103-1: Profiles - PROFIBUS (IEC 62769-103-1:2020)

Intégration des appareils de terrain (FDI) - Partie 103-1: Profils - PROFIBUS (IEC 62769-103-1:2020) Feldgeräteintegration (FDI) Teil 103-1: Profile - PROFIBUS (IEC 62769-103-1:2020)

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European Committee for Electrotechnical Standardization Comité Européen de Normalisation Electrotechnique Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN IEC 62769-103-1:2020 (E)

## **European foreword**

The text of document 65E/622/CDV, future edition 2 of IEC 62769-103-1, prepared by SC 65E "Devices and integration in enterprise systems" of IEC/TC 65 "Industrial-process measurement, control and automation" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62769-103-1:2020.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2023-06-02

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The text of the International Standard IEC 62769-103-1:2020 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following note has to be added for the standard indicated:

IEC 61784-1 NOTE Harmonized as EN IEC 61784-1

EN IEC 62769-103-1:2020 (E)

# Annex ZA

(normative)

# Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

| <u>Publication</u>       | <u>Year</u>      | <u>Title</u>  | EN/HD           | <u>Year</u> |
|--------------------------|------------------|---|-----------------|-------------|
| IEC 61804                | series           | Function blocks (FB) for process control and electronic device description language (EDDL)                      | EN IEC 61804    | series      |
| IEC 62541-100            | 2015             | OPC Unified Architecture - Part 100:<br>Device Interface and suite 1.10:  | EN 62541-100    | 2015        |
| IEC 62769-2 <sup>1</sup> | -<br>https://sta | Field Device Integration (FDI) - Part 2:<br>FDI Client<br>andards.itch.ai/catalog/standards/sist/457e7080-f949- | -<br>454a-bf9f- | -           |
| IEC 62769-4 <sup>2</sup> | -                | Field Device Integration (FDI) Part 4. FDI Packages   | -               | -           |
| IEC 62769-5 <sup>3</sup> | -                | Field Device Integration (FDI) - Part 5:<br>FDI Information Model   | -               | -           |
| IEC 62769-7 <sup>4</sup> | -                | Field Device Integration (FDI) - Part 7: FDI Communication Devices  | -               | -           |
| PI Order No.<br>2.122    | 2008             | Specification for PROFIBUS - Device Description and Device Integration - Volume 1: GSD, V5.1, July 2008: GSD    | -               | -           |

<sup>&</sup>lt;sup>1</sup> Under preparation. Stage at the time of publication: IEC/RFDIS 62769-2:2020.

<sup>&</sup>lt;sup>2</sup> Under preparation. Stage at the time of publication: IEC/RFDIS 62769-4:2020.

<sup>&</sup>lt;sup>3</sup> Under preparation. Stage at the time of publication: IEC/RFDIS 62769-5:2020.

<sup>&</sup>lt;sup>4</sup> Under preparation. Stage at the time of publication: IEC/RFDIS 62769-7:2020.

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<u>SIST EN IEC 62769-103-1:2020</u> https://standards.iteh.ai/catalog/standards/sist/457e7080-f949-454a-bf9f-e7a500f6a32b/sist-en-iec-62769-103-1-2020



IEC 62769-103-1

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# INTERNATIONAL STANDARD

# NORME INTERNATIONALE



Field device integration (FDI) ANDARD PREVIEW Part 103-1: Profiles – PROFIBUS dards.iteh.ai)

Intégration des appareils de terrain (FDI) 5-103-1:2020
Partie 103-1: Profils/starPROFIBUS log/standards/sist/457e7080-f949-454a-bf9f-e7a500f6a32b/sist-en-iec-62769-103-1-2020

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### INTERNATIONAL ELECTROTECHNICAL COMMISSION

## FIELD DEVICE INTEGRATION (FDI) -

Part 103-1: Profiles - PROFIBUS

## **FOREWORD**

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International Standard IEC 62769-103-1 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation.

This second edition cancels and replaces the first edition published in 2015. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) support for generic protocol extension for faster adoption of other technologies;
- b) support for Package Developers to build EDDs targeted for today's EDD bases system under a single development tool.

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The text of this International Standard is based on the following documents:

| CDV         | Report on voting            |
|-------------|-----------------------------|
| 65E/622/CDV | 65E/685A/RVC<br>65E/685/RVC |

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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## FIELD DEVICE INTEGRATION (FDI) -

## Part 103-1: Profiles - PROFIBUS

#### 1 Scope

This part of IEC 62769 specifies an FDI profile of IEC 62769 for IEC 61784-1\_CP 3/1 (PROFIBUS DP)<sup>1</sup> and IEC 61784-1\_CP3/2 (PROFIBUS PA)<sup>1</sup>.

#### 2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61804 (all parts), Function blocks (FB) for process control and Electronic Device Description Language (EDDL)

IEC 62541-100:2015, OPC Unified Architecture - Part 100: Device Interface

IEC 62769-22, Field Device Integration (FDI) - Part 2: FDI Client

IEC 62769-43, Field Device Integration (FDI) OPart 13 FDI Packages https://standards.iteh.ai/catalog/standards/sist/457e7080-f949-454a-bf9f-

IEC 62769-54, Field Device Integration (FDI) - Part 5. FDI Information Model

IEC 62769-75, Field Device Integration (FDI) – Part 7: FDI Communication Devices

PI Order No.: 2.122:2008, Specification for PROFIBUS – Device Description and Device Integration – Volume 1: GSD, V5.1, July 2008: GSD; available at <www.profibus.com> [viewed 2018-11-23]

### 3 Terms, definitions, abbreviated terms and conventions

### 3.1 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 61784-1, IEC 61804 (all parts), IEC 62541-100, IEC 62769-4, IEC 62769-5, IEC 62769-7 and PI Order No.: 2.122:2008 apply.

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<sup>2</sup> Under preparation. Stage at the time of publication: IEC/RFDIS 62769-2:2020.

<sup>3</sup> Under preparation. Stage at the time of publication: IEC/RFDIS 62769-4:2020.

<sup>4</sup> Under preparation. Stage at the time of publication: IEC/RFDIS 62769-5:2020.

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